2SB1025

Silicon PNP Epitaxial

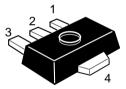
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Application

- Low frequency power amplifier
- Complementary pair with 2SD1418

Outline

UPAK



- 1. Base
- 2. Collector
- 3. Emitter
- 4. Collector (Flange)



2SB1025

Absolute Maximum Ratings (Ta = 25°C)

Item	Symbol	Ratings	Unit
Collector to base voltage	V_{CBO}	-120	V
Collector to emitter voltage	V_{CEO}	-80	V
Emitter to base voltage	V _{EBO}	- 5	V
Collector current	Ic	–1	A
Collector peak current	i _{C(peak)} *1	-2	A
Collector power dissipation	P _c * ²	1	W
Junction temperature	Tj	150	°C
Storage temperature	Tstg	-55 to +150	°C

Notes: 1. PW ≤ 10 ms, Duty cycle ≤ 20%

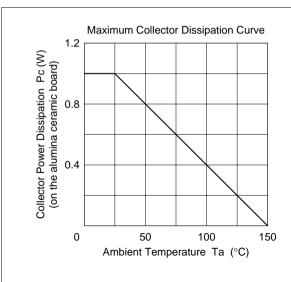
2. Value on the alumina ceramic board (12.5 \times 20 \times 0.7 mm)

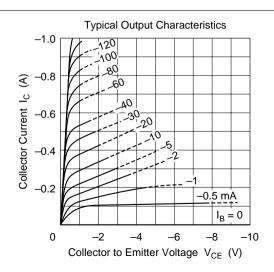
Electrical Characteristics ($Ta = 25^{\circ}C$)

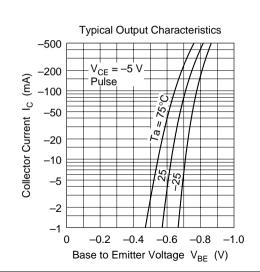
Item	Symbol	Min	Тур	Max	Unit	Test conditions
Collector to base breakdown voltage	$V_{(BR)CBO}$	-120	_	_	V	$I_{c} = -10 \ \mu A, \ I_{E} = 0$
Collector to emitter breakdown voltage	$V_{(BR)CEO}$	-80	_	_	V	$I_{C} = -1 \text{ mA}, R_{BE} = \infty$
Emitter to base breakdown voltage	$V_{(BR)EBO}$	- 5	_	_	V	$I_{E} = -10 \mu\text{A}, I_{C} = 0$
Collector cutoff current	I _{CBO}	_	_	-10	μΑ	$V_{CB} = -100 \text{ V}, I_{E} = 0$
DC current transfer ratio	h _{FE1} *1	60	_	320		$V_{CE} = -5 \text{ V}, I_{C} = -150 \text{ mA}$
	h _{FE2}	30	-	_		$V_{CE} = -5 \text{ V},$ $I_{C} = -500 \text{ mA (Pulse test)}$
Collector to emitter saturation voltage	V _{CE(sat)}	_	_	– 1	V	$I_C = -500 \text{ mA},$ $I_B = -50 \text{ mA (Pulse test)}$
Base to emitter voltage	V_{BE}	_	_	-0.9	V	$V_{CE} = -5 \text{ V}, I_{C} = -150 \text{ mA}$
Gain bandwidth product	f _T	_	140	_	MHz	$V_{CE} = -5 \text{ V}, I_{C} = -150 \text{ mA}$
Collector output capacitance	Cob	_	20	_	pF	$V_{CB} = -10 \text{ V}, I_{E} = 0,$ f = 1 MHz

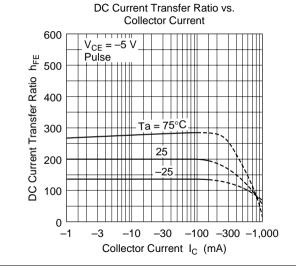
Note: 1. The 2SB1025 is grouped by $h_{\rm FE1}$ as follows.

Mark	DH	DJ	DK
h _{FE1}	60 to 120	100 to 200	160 to 320

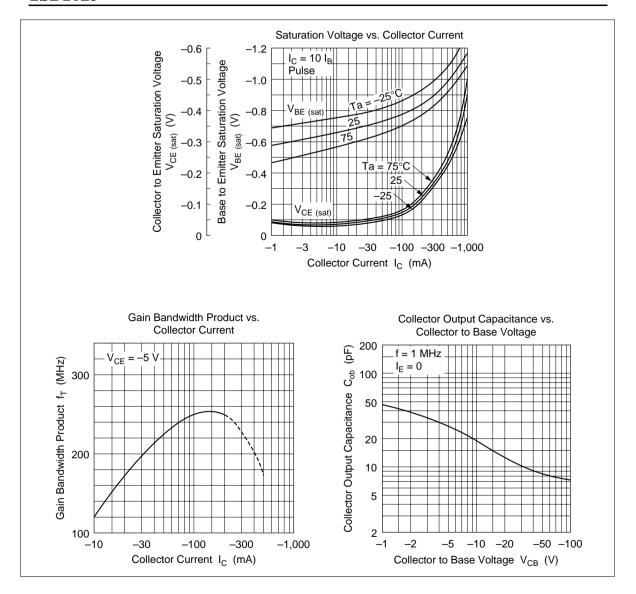




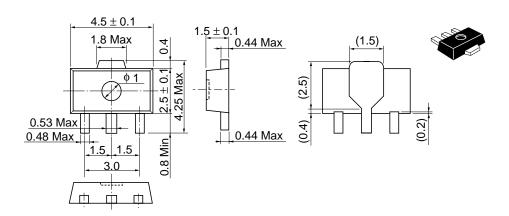




2SB1025



Unit: mm



Hitachi Code	UPAK
JEDEC	_
EIAJ	Conforms
Weight (reference value)	0.050 g

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